

## 100V N-Channel SGT MOSFET

### **General Description**

#### • Trench Power SGT technology

- Very low on-resistance R<sub>DS(ON)</sub>
- Low Gate Charge
- Excellent Gate Charge x R<sub>DS(ON)</sub> Product

### **Applications**

• High Frequency Switching and Synchronous Rectification

### **Product Summary**

 $V_{\text{DS}}$ 100V  $I_D$  (at  $V_{GS} = 10V$ ) 55A  $R_{DS(ON)}$  (at  $V_{GS} = 10V$ ) < 12mΩ

 $R_{DS(ON)}$  (at  $V_{GS} = 4.5V$ ) < 15mΩ

100% UIS Tested 100% DVDS Tested







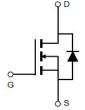




DFN5x6







Part Number	Package Type	Form	Marking
TSD120N10AT	TO-252	Tape&Reel	TSD120N10AT
TSP120N10AT	TO-220	Tube	TSP120N10AT
TSG120N10AT	DFN5x6	Tape&Reel	TSG120N10AT

# Absolute Maximum Ratings (T<sub>A</sub> =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		$V_{GS}$	±20	V	
Continuous Drain Current B	T <sub>C</sub> =25°C		55	٨	
Continuous Drain Current B	T <sub>C</sub> =100°C	ID	39	Α	
Pulsed Drain Current A		I <sub>DM</sub>	220	А	
Avalanche Current A		I <sub>AS</sub>	20	Α	
Single Pulse Avalanche Energy L =0.3mH A		E <sub>AS</sub>	60	mJ	
Power Dissipation $^{\text{C}}$ $ T_{\text{C}} = 25^{\circ}\text{C} $ $ T_{\text{C}} = 100^{\circ}\text{C} $		P <sub>D</sub>	83.3	W	
			41.7	W	
Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 175	°C	
Thermal Characteristics					

Thermal Gharacteristics						
Parameter		Symbol	Maximum	Units		
Maximum Junction-to-Case	to-Case Steady-State R <sub>eJC</sub> 1.8		°C/W			
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	50	-C/VV		





Oh a l	Baramatar	0 - 11 414 - 11 -		Value			Units
Symbol	Parameter Conditions			Min	Тур	Max	Units
STATIC P	ARAMETERS						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$		100			٧
		T <sub>J</sub> =25°C			1		
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	T <sub>J</sub> =125°C			100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$				±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		1.1	1.6	2.4	V
_		V <sub>GS</sub> =10V, I <sub>D</sub> =30A		100 ±100	12	mΩ	
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =30A			12	15	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A			32		S
$V_{SD}$	Diode Forward Voltage	I <sub>S</sub> =30A, V <sub>GS</sub> =0V				1	V
Is	Maximum Body-Diode Continuous Curre	Maximum Body-Diode Continuous Current <sup>B</sup>				55	Α
DYNAMIC	PARAMETERS						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =50V, f =1MH <sub>Z</sub>			1766		pF
C <sub>oss</sub>	Output Capacitance				201		
C <sub>rss</sub>	Reverse Transfer Capacitance				4.1		
$R_g$	Gate Resistance	f=1MH <sub>Z</sub>			2.3		Ω
SWITCHIN	IG PARAMETERS						
Q <sub>g</sub> (10V)	Total Gate Charge				25.7		
Q <sub>g</sub> (4.5V)	Gate Source Charge	V <sub>GS</sub> =10V,V <sub>DS</sub> =50V, I <sub>E</sub>	-204		13		nC
$Q_{gs}$	Gate Source Charge		) -20A		4.3		
$Q_{gd}$	Gate Drain Charge				5.3		
Q <sub>oss</sub>	Output Charge	V <sub>GS</sub> =0V,V <sub>DS</sub> =50V			34.2		
$t_{D(on)}$	Turn-On Delay Time				33		
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DS} = 50V, I_{D} = 20A,$ $R_{G} = 1.8\Omega$			4		ns
$t_{D(off)}$	Turn-Off Delay Time				55		113
t <sub>f</sub>	Turn-Off Fall Time				3.1		
t <sub>rr</sub>	Body Diode Reverse Recovery Time	1 =20A di/dt =400A/:	0		49		ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	$I_F = 20A$ , di/dt = $100A/\mu$	S		71		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation  $P_D$  is based on  $T_{J(MAX)}$ =175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

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#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

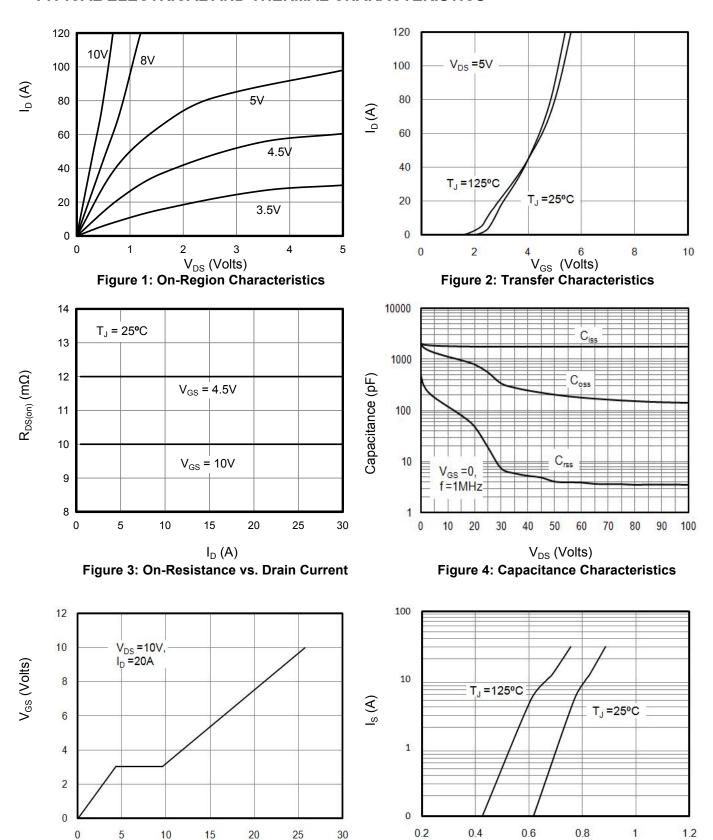


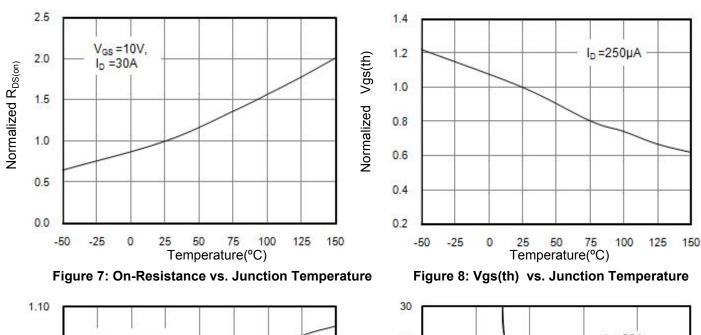
Figure 5: Gate Charge Characteristics Figure 6: Body Diode Forward Voltage

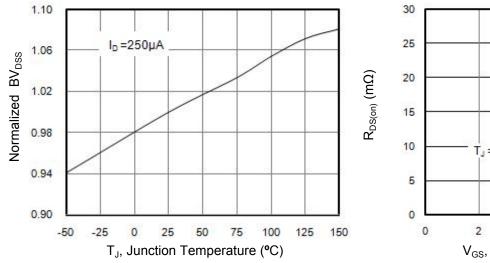
V<sub>SD</sub> (Volts)

 $Q_g$  (nC)



#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS





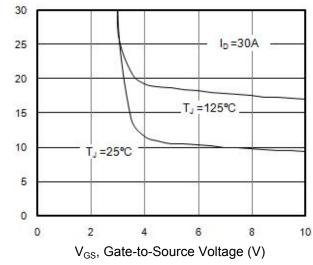


Figure 10: On-Resistance vs. Gate-Source Voltage

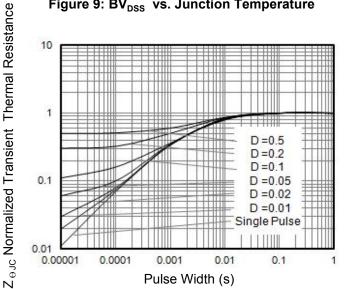


Figure 9: BV<sub>DSS</sub> vs. Junction Temperature

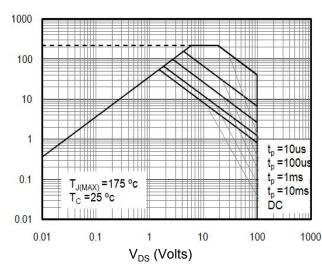


Figure 11: Normalized Transient Thermal Resistance

Figure 12: Safe Operating Area

l<sub>D</sub> (Amps)



Figure A: Gate Charge Test Circuit and Waveforms

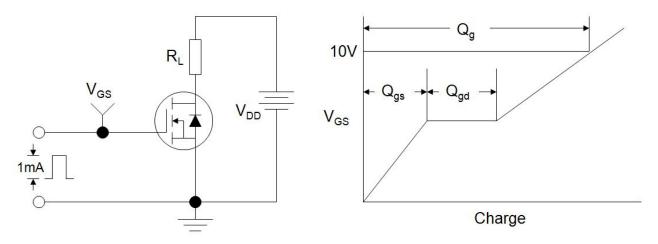


Figure B: Resistive Switching Test Circuit and Waveforms

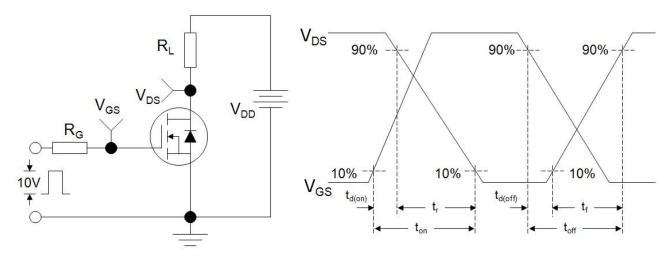
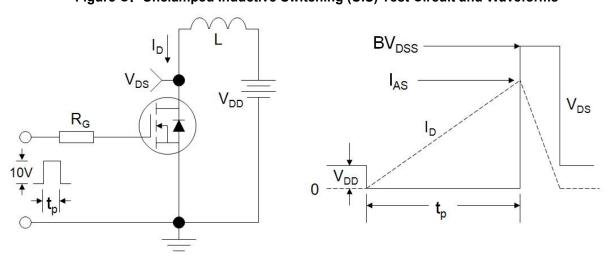


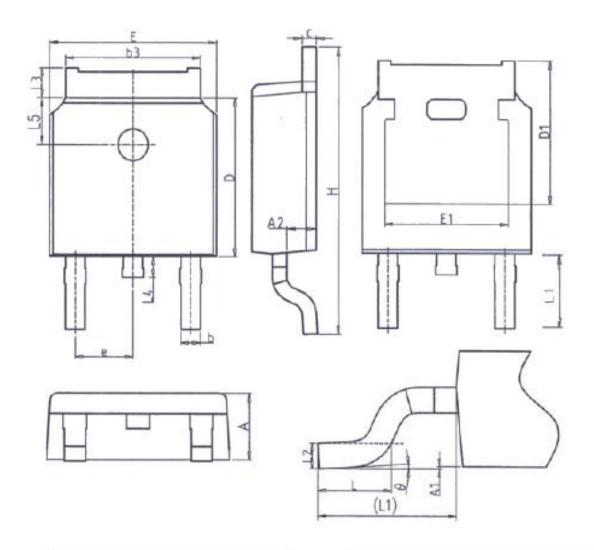
Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms



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# **TO-252**

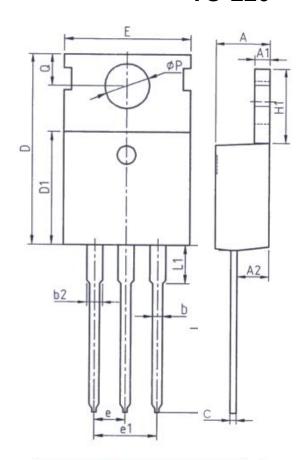


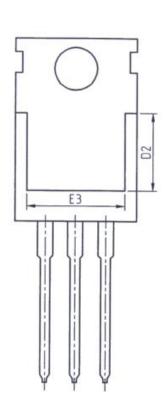
Symbol	Min	Nom	Max	
Α	2.20	2.30	2.38	
A1	0.00		0.10	
A2	0.90	1.01	1.10	
b	0.72		0.85	
b3	5.13	5.33	5.46	
С	0.47		0.60	
D	6.00	6.10	6.20	
D1	5.25 REF			
E	6.50	6.60	6.70	
E1	4.70	29	. 0	

Unit:	mm			
Min	Nom	Max		
	2.286BSC			
9.80	10.10	10.40		
1.40	1.50	1.70		
2.90REF				
0.508BSC				
0.90	~~~ <u>~</u>	1.25		
0.60	0.80	1.00		
1.8 REF				
O° - 8				
	9.80 1.40	2.286BSC 9.80 10.10 1.40 1.50 2.90REF 0.508BSC 0.90 - 0.60 0.80		



## **TO-220**





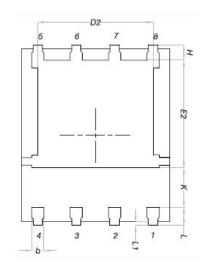
U	Unit: mm					
Symbol	Min.	Max.				
Α	4. 37	4. 77				
A1	1. 25	1. 45				
A2	2. 20	2. 60				
b	0.70	0.95				
b2	1. 17	1. 47				
С	0.40	0.65				
D	15. 10	16. 10				
D1	8. 80	9. 40				
D2	5. 50	-				

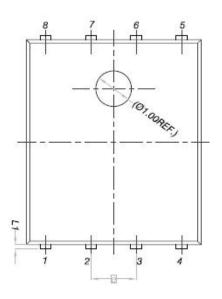
	Unit: mm	1			
Symbol	Min.	Max.			
Ε	9.70	10.30			
E3	7.00	573			
е	2. 54BSC				
e1	5. 08BSC				
H1	6. 25 6. 85				
L	12. 75	13.80			
L1		3. 40			
Р	3. 40	3.80			
Q	2.60	3.00			

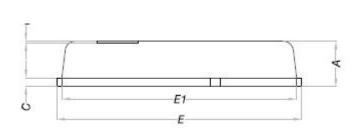
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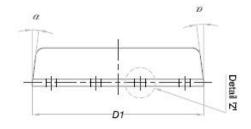


## DFN5x6









DIM.	MILLIMETERS	544	MILLIMETERS				
	NOM.	MAX.	DIM.	MIN.	NOM.	MAX.	
Α	0.90	1.00	1.10	E	5.90	6.00	6.10
A1	0	-	0.05	E1	5.70	5.75	5.80
b	0.33	0.41	0.51	E2	3.38	3.58	3.78
С	0.20	0.25	0.30	е	1.27 BSC		
D1	4.80	4.90	5.00	Н	0.41	0.51	0.61
D2	3.61	3.81	3.96	К	1.10	( <del>=</del> )	-
				L	0.51	0.61	0.71
				L1	0.06	0.13	0.20
				α	O°	-	12°

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#### TSD120N10AT,TSP120N10AT,TSG120N10AT



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